

ABSTRACT OF THE DISCLOSURE

5 An electronic circuit module formed of an antenna coil and an
integrated circuit provided on a circuit board is provided inside a hollow
resin case formed of a first part and a second part. A first slit leading into
the hollow portion is provided in one side face of the resin case formed of the
first and second parts joined to each other. Since the electronic circuit
module is not exposed to high temperatures and high pressure during the
manufacturing process, defects such as the breakage of the integrated circuit
10 or the disconnection of the antenna coil can be avoided. Since the slit
leading into the hollow portion is provided, the hollow portion does not swell
by the temperature increase. In addition, pinholes do not tend to be formed
during the joining of the first and second parts. Thus, a contactless data
carrier with an excellent electrostatic withstand voltage characteristic can be
15 provided.

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